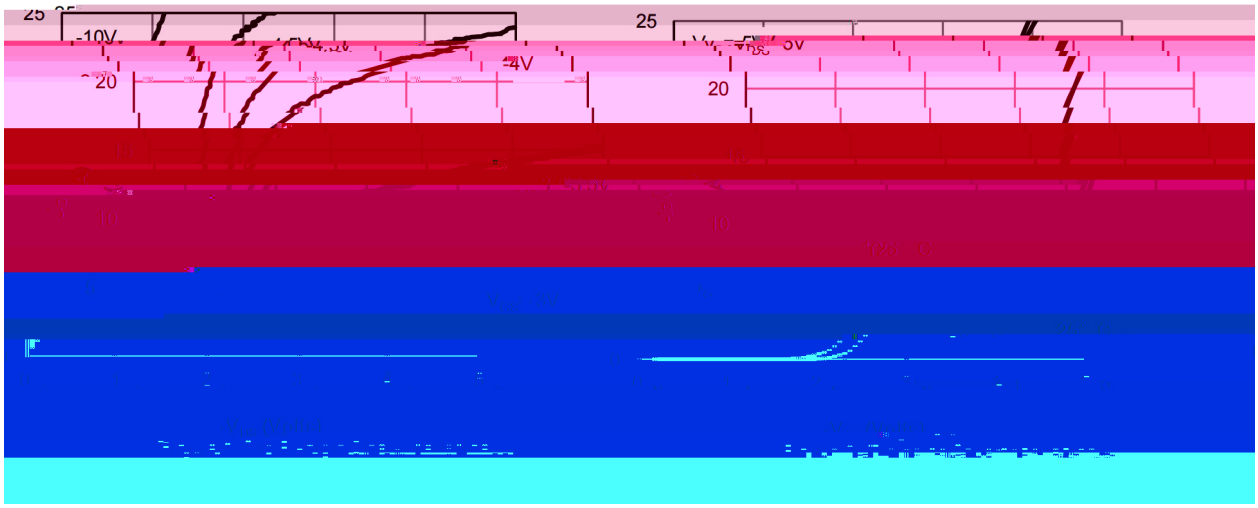
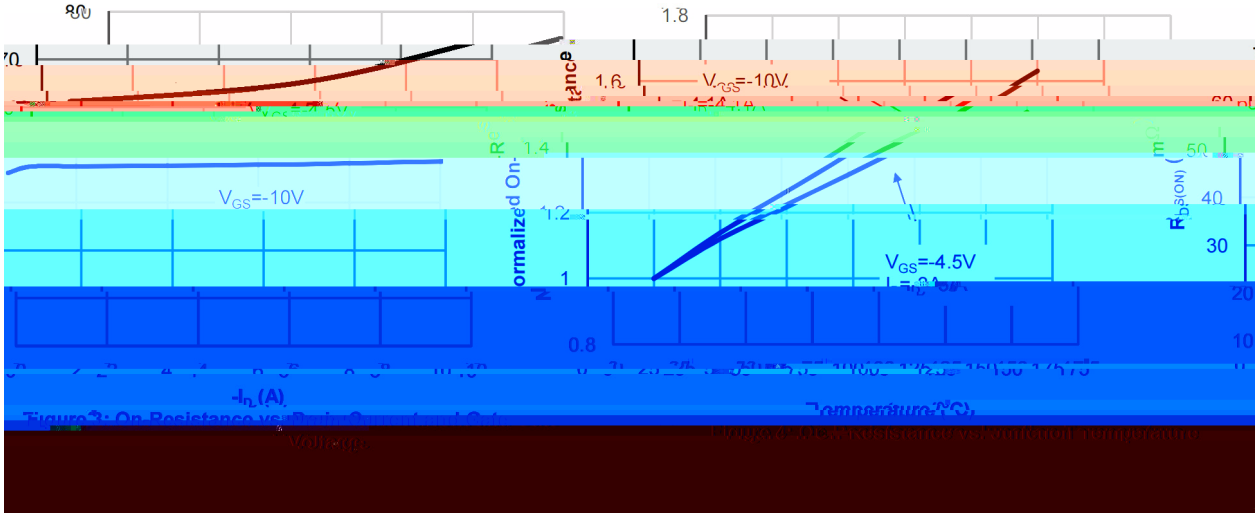
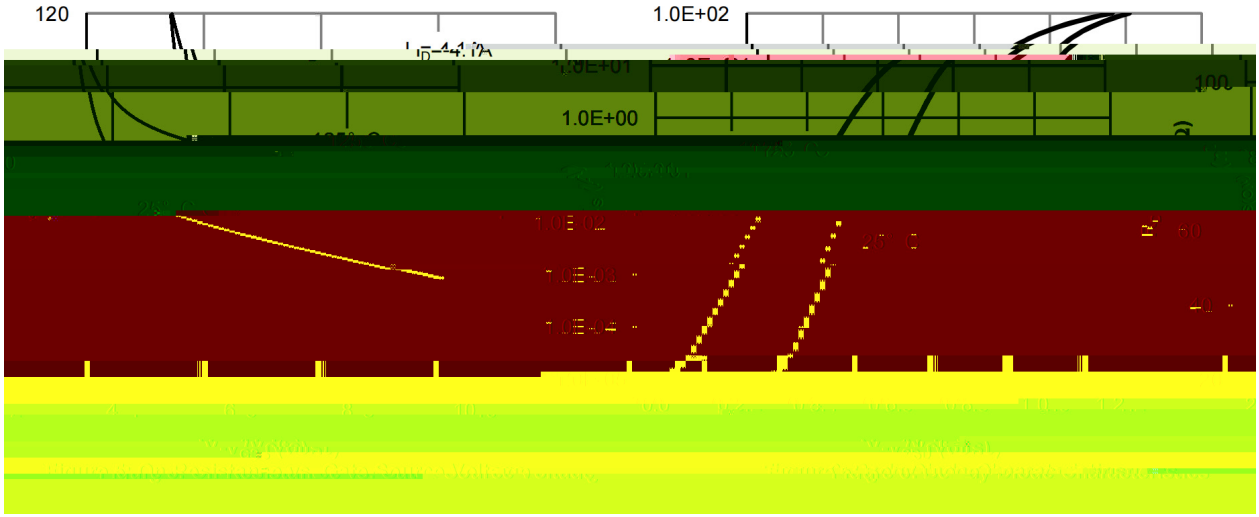
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Total Gate Charge	Q_g(10V)	V_{GS}=-10V, V_{DS}=-15V, I_D=-4.1A		8.5		nC
Total Gate Charge	Q_g(4.5V)			4.5		
Gate Source Charge	Q_{gs}			1.5		
Gate Drain Charge	Q_{gd}			2.0		
Turn–On Delay Time	$t_{d(on)}$					

V_{GSg}

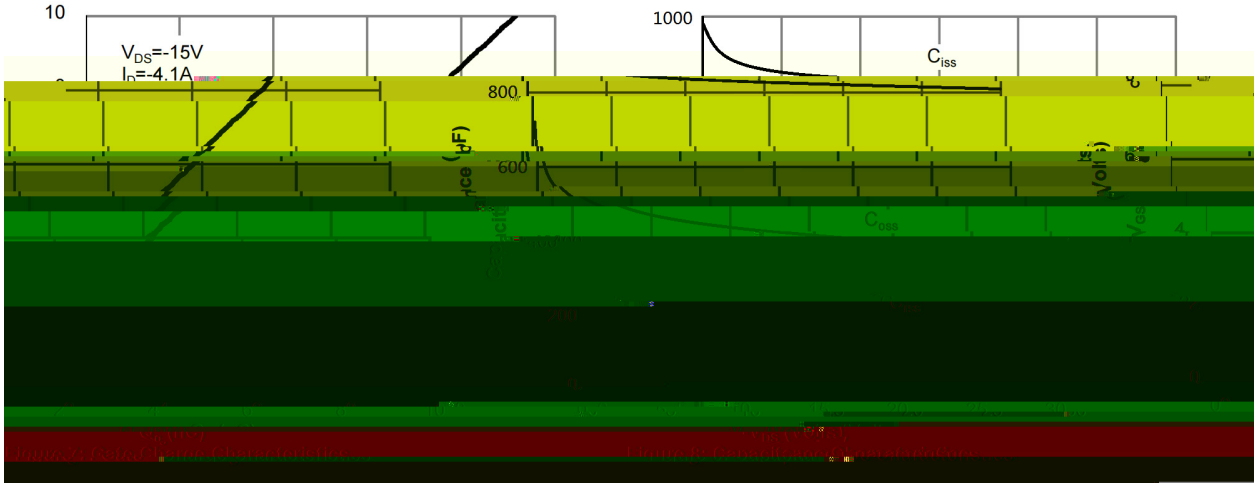
/ Electrical Characteristic Curve







/ Electrical Characteristic Curve



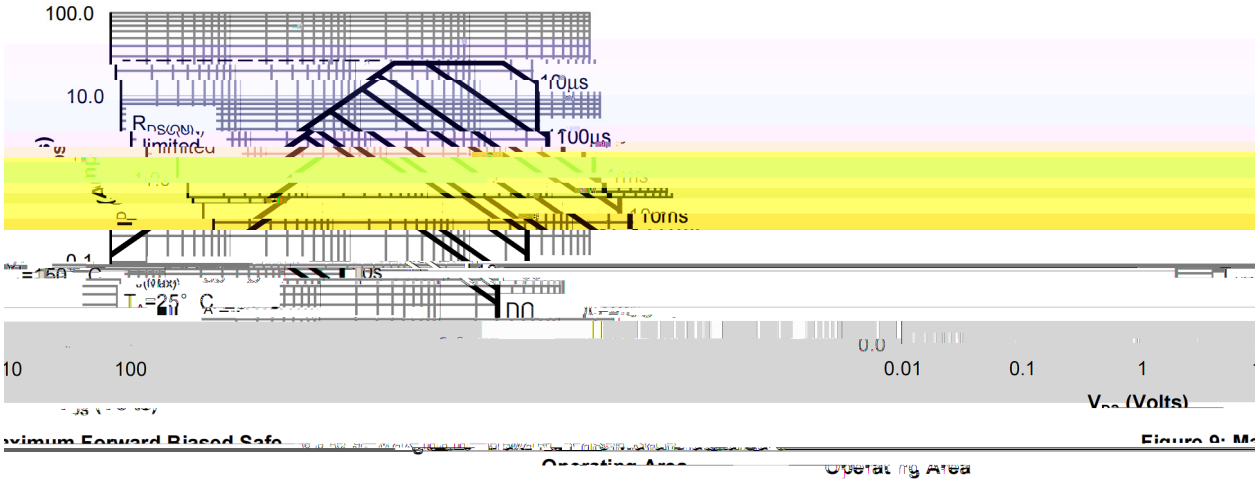
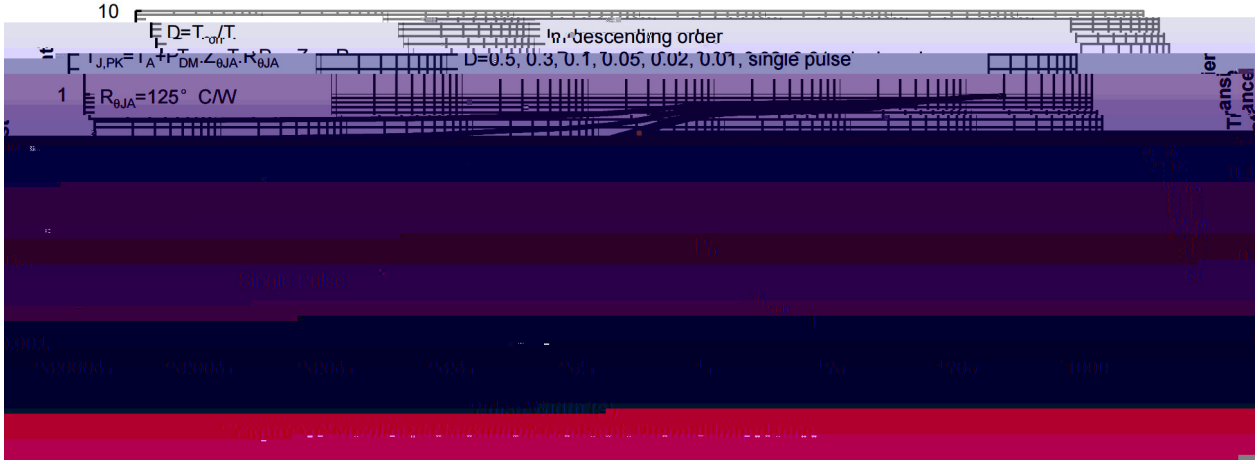
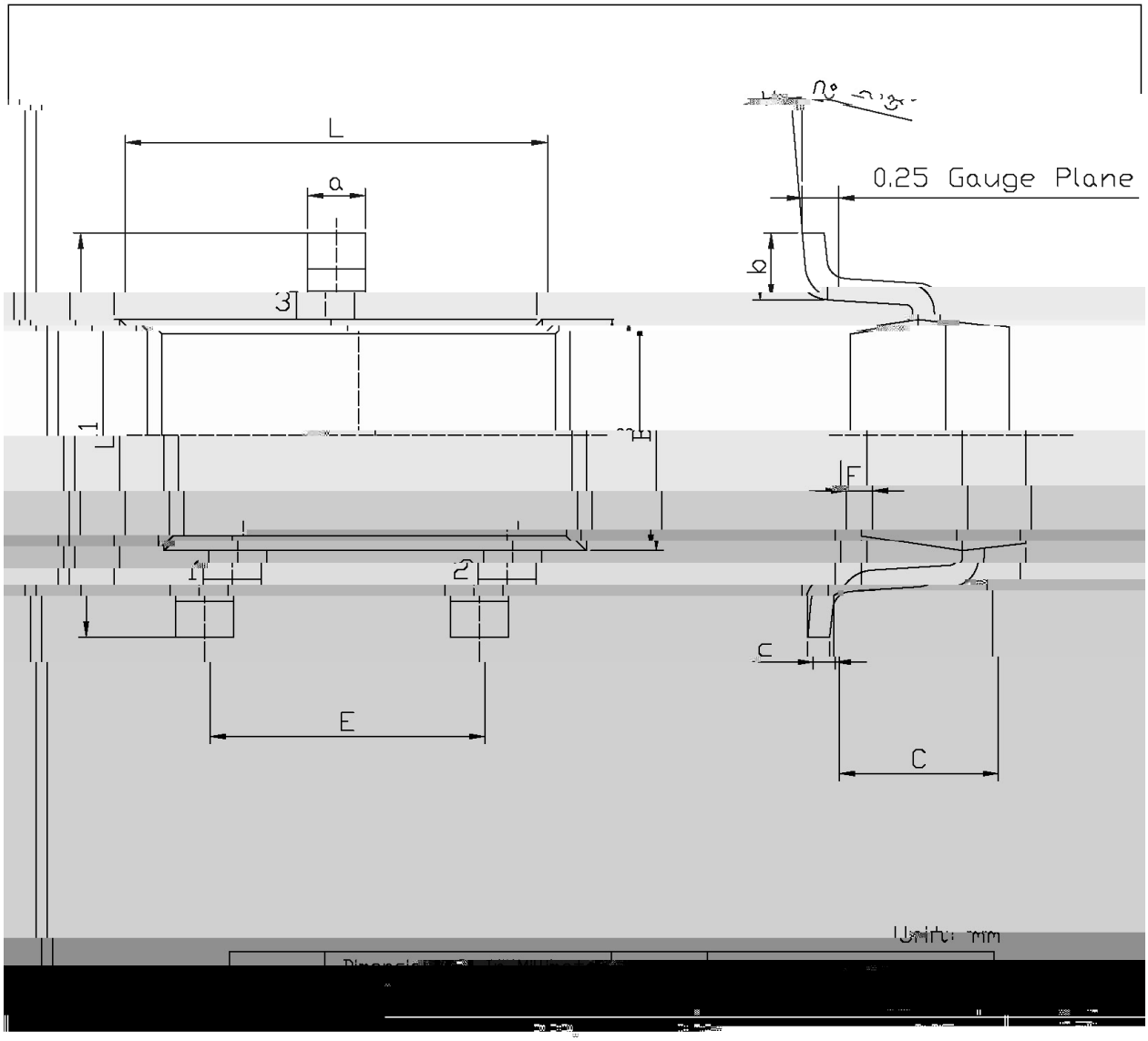


Figure 9: Maximum Forward Biased Safe Operating Area



/ Package Dimensions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

		Note:
1	150 180 60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245 5 5 0.5sec;	2.Peak Temp.:245 5 , Duration:5 0.5sec.
3	2 10 /sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5	10 1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL